



MICROWAVE CORPORATION v02.0705



HMC433 / 433E

SMT GaAs HBT MMIC
DIVIDE-BY-4, DC - 8.0 GHz

Typical Applications

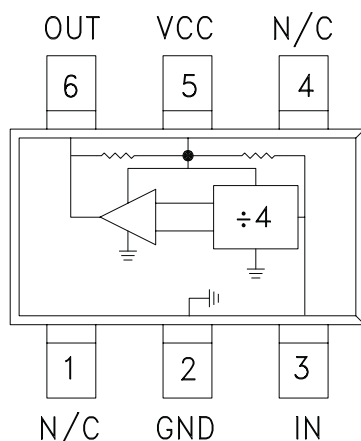
Prescaler for DC to C Band PLL Applications:

- UNII, Point-to-Point & VSAT Radios
- 802.11a & HiperLAN WLAN
- Fiber Optic
- Cellular / 3G Infrastructure

Features

Ultra Low SSB Phase Noise: -150 dBc/Hz
Single-Ended I/O's
Output Power: -2 to -3.5 dBm
Single DC Supply: +3V @ 53 mA
9 mm² Ultra Small Package: SOT26

Functional Diagram



General Description

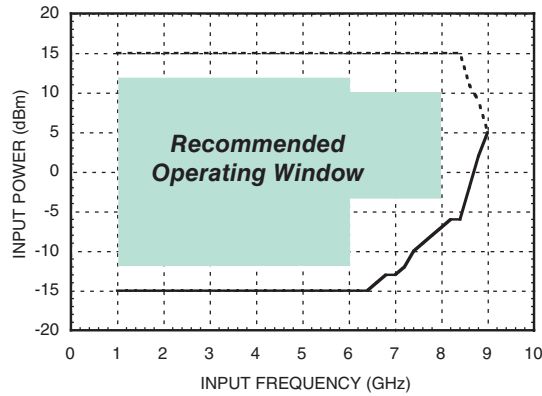
The HMC433 & HMC433E are low noise Divide-by-4 Static Dividers utilizing InGaP GaAs HBT technology in ultra small surface mount SOT26 plastic packages. This device operates from DC (with a square wave input) to 8.0 GHz input frequency with a single +3.0V DC supply. Single-ended inputs and outputs reduce component count and cost. The low additive SSB phase noise of -150 dBc/Hz at 100 kHz offset helps the user maintain good system noise performance.

Electrical Specifications, $T_A = +25^\circ\text{C}$, 50 Ohm System, $V_{CC} = +3V$

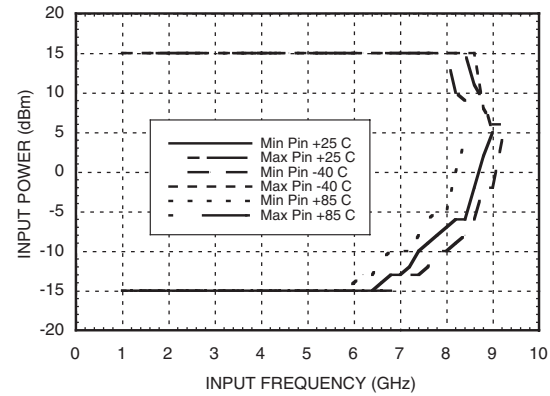
Parameter	Conditions	Min.	Typ.	Max.	Units
Maximum Input Frequency		8	8.5		GHz
Minimum Input Frequency	Sine Wave Input. [1]		0.2		GHz
Input Power Range	$F_{in} = 1 \text{ to } 6 \text{ GHz}$	-12	-15	+12	dBm
	$F_{in} = 6 \text{ to } 8 \text{ GHz}$	-3	-7	+10	dBm
Output Power	$F_{in} = 4 \text{ GHz}$	-5.0	-2.0		dBm
	$F_{in} = 8 \text{ GHz}$	-6.5	-3.5		dBm
Reverse Leakage	RF Output Terminated, $F_{in} = 4 \text{ GHz}$, $P_{in} = 0 \text{ dBm}$		-25		dBm
SSB Phase Noise (100 kHz offset)	$P_{in} = 0 \text{ dBm}$, $F_{in} = 4 \text{ GHz}$		-150		dBc/Hz
Output Transition Time	$P_{in} = 0 \text{ dBm}$, $F_{out} = 882 \text{ MHz}$		120		ps
Supply Current (I_{CC})	$V_{CC} = +3.0V$		53		mA

1. Divider will operate down to DC for square-wave input signal.

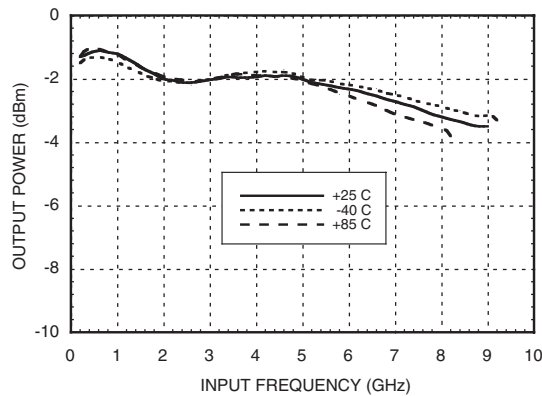
Input Sensitivity Window, $T = 25^\circ\text{C}$



Input Sensitivity Window vs. Temperature

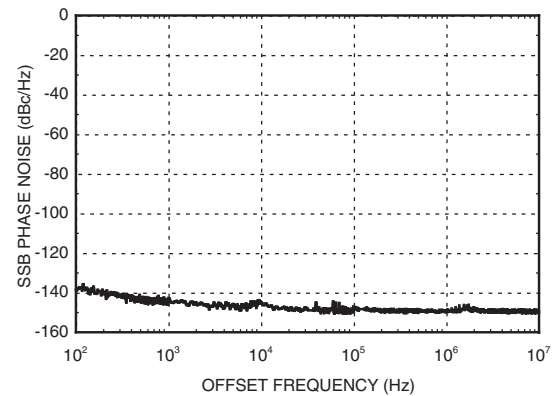


Output Power vs. Temperature



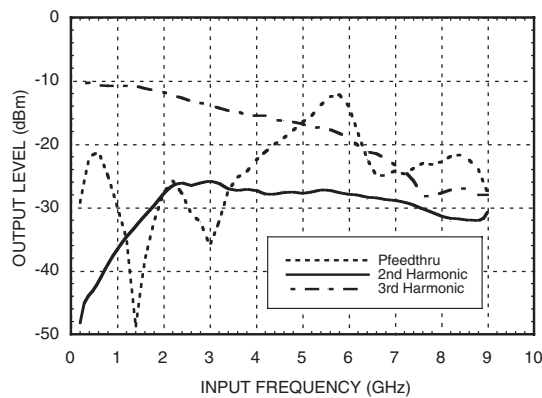
SSB Phase Noise

Performance, $P_{in} = 0\text{ dBm}$, $T = 25^\circ\text{C}$

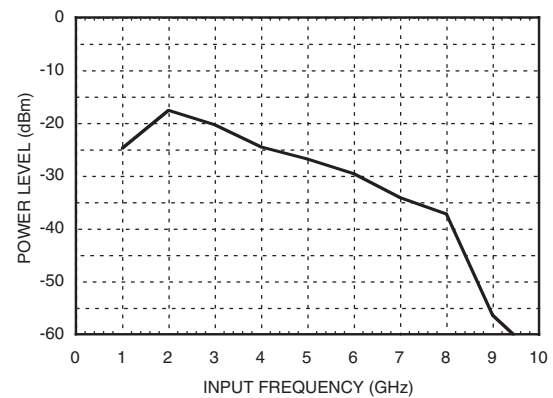


Output Harmonic

Content, $P_{in} = 0\text{ dBm}$, $T = 25^\circ\text{C}$



Reverse Leakage, $P_{in} = 0\text{ dBm}$, $T = 25^\circ\text{C}$





MICROWAVE CORPORATION

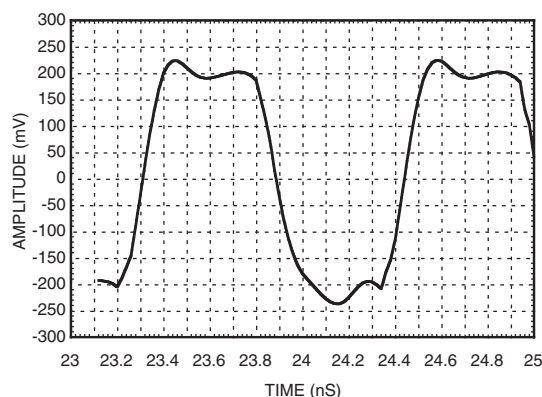
v02.0705



HMC433 / 433E

SMT GaAs HBT MMIC
DIVIDE-BY-4, DC - 8.0 GHz

Output Voltage Waveform,
 $P_{in} = 0 \text{ dBm}$, $F_{out} = 882 \text{ MHz}$, $T = 25^\circ\text{C}$

**Absolute Maximum Ratings**

RF Input ($V_{cc} = +3.0\text{V}$)	+15 dBm
V_{cc}	+3.5V
Maximum Channel Temperature	135 °C
Continuous P_{diss} ($T = 85^\circ\text{C}$) (derate 5mW/°C above 85 °C)	250mW
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C
ESD Sensitivity (HBM)	Class 1A

DC blocking capacitors are required at RF input and RF output ports.
 Choose value for lowest frequency of operation.

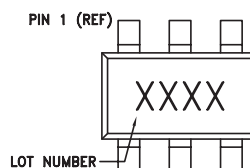
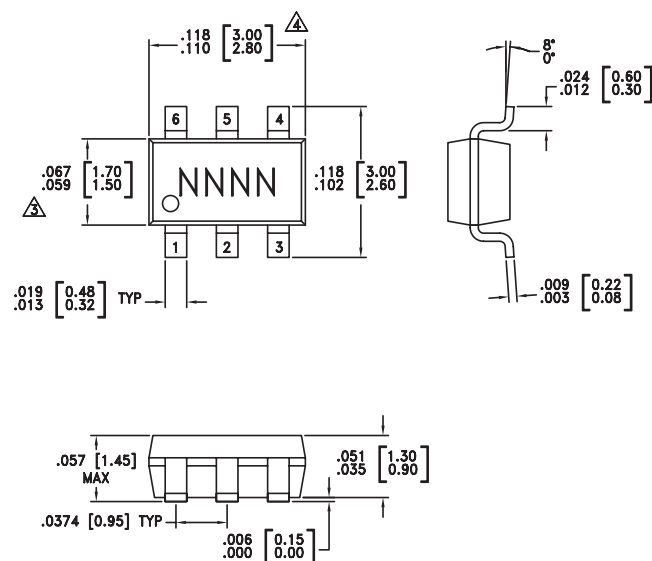


ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

Typical Supply Current vs. V_{cc}

V_{cc} (V)	I_{cc} (mA)
2.70	42
3.0	53
3.30	63

Note: Divider will operate over full voltage range shown above

Outline Drawing**NOTES:**

1. LEADFRAME MATERIAL: COPPER ALLOY
2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
3. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
4. PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM.
PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
5. PACKAGE WARP SHALL NOT EXCEED 0.05mm.
6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
7. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED LAND PATTERN.

Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking ^[3]
HMC433	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 ^[1]	H433 XXXX
HMC433E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 ^[2]	433E XXXX

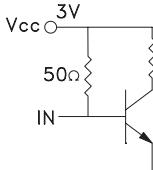
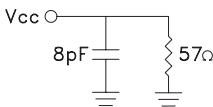
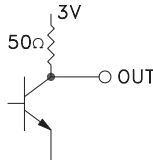
[1] Max peak reflow temperature of 235 °C

[2] Max peak reflow temperature of 260 °C

[3] 4-Digit lot number XXXX

For price, delivery, and to place orders, please contact Hittite Microwave Corporation:
 20 Alpha Road, Chelmsford, MA 01824 Phone: 978-250-3343 Fax: 978-250-3373
 Order On-line at www.hittite.com

Pin Description

Pin Number	Function	Description	Interface Schematic
1, 4	N/C	No Connection	
2	GND	Pin must connect to RF/DC ground.	
3	IN	RF input must be DC blocked.	
5	Vcc	Supply voltage 3V ± 0.3V.	
6	OUT	Divided output must be DC blocked.	



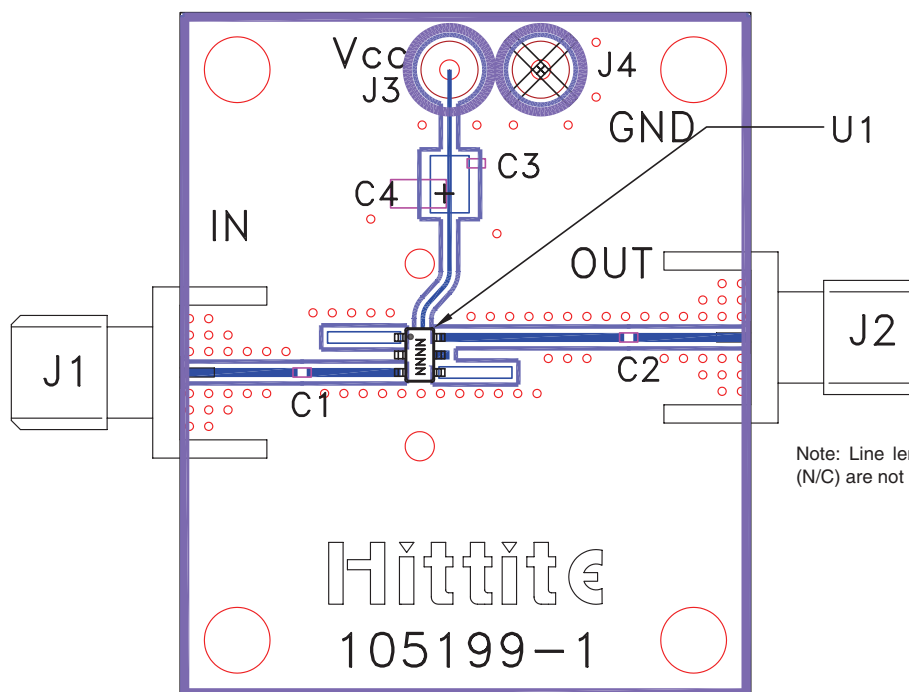
MICROWAVE CORPORATION v02.0705



HMC433 / 433E

SMT GaAs HBT MMIC
DIVIDE-BY-4, DC - 8.0 GHz

Evaluation PCB



List of Materials for Evaluation PCB 105675 ^[1]

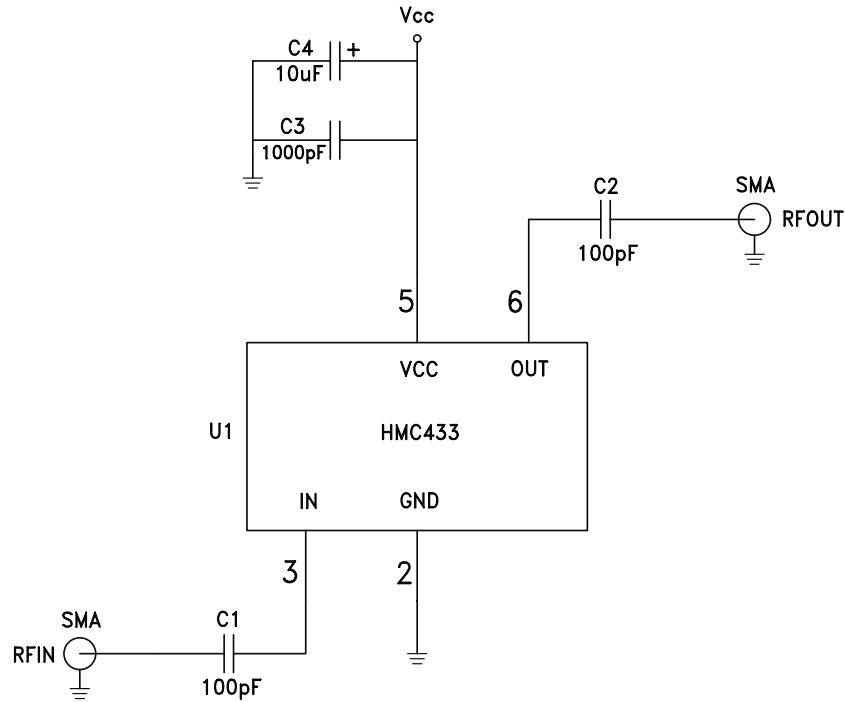
Item	Description
J1 - J2	PCB Mount SMA RF Connector
J3 - J4	DC Pin
C1 - C2	100 pF Capacitor, 0402 Pkg.
C3	1000 pF Capacitor, 0402 Pkg.
C4	10 μ F Tantalum Capacitor, 1206 Pkg.
U1	HMC433 / HMC433E Divide-by-4
PCB ^[2]	105199 Eval Board

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.

Application Circuit



Note:

DC blocking capacitor values (C1, C2) and DC decoupling capacitor values (C3, C4) are chosen for lowest frequency of operation.